

Amendments to the claims:

Claims 1-9 (Canceled). Please add the following claims:

10. (Previously presented) Method for producing an electronic module in the shape of a ball housing combining a network of interconnection or shielding balls (7) or geometrically identical preforms and surface-mounted components (2) on the same side of a substrate (1), thus making the module directly connectable to a printed circuit (3), wherein:

soldering cream (8) is deposited simultaneously for the components and the interconnection or shielding balls located on the same surface;

the said components are transferred onto the corresponding mounting lands;

the interconnection balls are transferred collectively onto the lands of the same side intended for them by an appropriate device; and

a single reflow cycle permits simultaneous soldering of the components and the interconnection or shielding balls onto the substrate.

11. (Previously presented) Method as claimed in claim 10, wherein the soldering cream (8) is deposited via serigraphy.

12. (Previously presented) Method as claimed in claim 10, wherein the soldering cream (8) is deposited by syringe.

13. (Previously presented) Method as claimed in claim 10, the circuit having a ground plane, wherein it makes it possible to produce an electromagnetic shield integrated directly into the electronic module by conducting connections (19)(21) to the ground plane (20) of the circuit (3).

14. (Previously presented) Method as claimed in claim 10, wherein it makes it possible to integrate as close to the connecting balls (7) as possible and on the same side of the electronic module decoupling capacitors (17) and/or serial resistors (16) and/or filtering cells and/or quartz adapter condensers.

15. (Previously presented) Method as claimed in claims 10, wherein the side of the module opposite the side comprising the balls and the components allows gripping of the module by suction.

Claims 16-18 (Canceled).

19. (Previously presented) Method as claimed in claim 10, the module being directly connectable by soldering to the printed circuit.
20. (Previously presented) Method as claimed in claim 10, wherein the interconnection or shielding balls have a diameter greater than the height of said components.